

Taiwan Semiconductor

2A, 200V - 1000V Fast Recovery Surface Mount Rectifier

FEATURES

- Glass passivated chip junction
- Ideal for automated placement
- Low reverse leakage
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- DC to DC converter
- Switching mode converters and inverters
- General purpose

MECHANICAL DATA

- Case: SMAF
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 1 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.035g (approximately)

KEY PARAMETERS				
PARAMETER	VALUE	UNIT		
١ _F	2	А		
V _{RRM}	200 - 1000	V		
I _{FSM}	50	А		
T _{J MAX}	150	°C		
Package	SMAF			
Configuration	Single die			







ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)								
PARAMETER		SYMBOL	RS	RS	RS	RS	RS	UNIT
			2DAF-T	2GAF-T	2JAF-T	2KAF-T	2MAF-T	
Marking code on the de	vice		RS2DAF	RS2GAF	RS2JAF	RS2KAF	RS2MAF	
Repetitive peak reverse	voltage	V_{RRM}	200	400	600	800	1000	V
Reverse voltage, total r	ns value	$V_{R(RMS)}$	140	280	420	560	700	V
Forward current		I _F			2			А
Surge peak forward current single half sine-	t = 8.3ms	1			50			А
wave superimposed on rated load	t = 1.0ms	I _{FSM}			130			А
Junction temperature	Junction temperature T _J		-55 to +150					°C
Storage temperature		T _{STG}	-55 to +150		°C			



THERMAL PERFORMANCE				
PARAMETER	SYMBOL	ТҮР	UNIT	
Junction-to-lead thermal resistance	R _{ƏJL}	15	°C/W	
Junction-to-ambient thermal resistance	R _{eja}	89	°C/W	
Junction-to-case thermal resistance	R _{eJC}	22	°C/W	

Thermal Performance Note: Units mounted on PCB (5mm x 5mm Cu pad test board)

PARAMETER		CONDITIONS	SYMBOL	ТҮР	MAX	UNIT
		$I_F = 1A, T_J = 25^{\circ}C$		0.86	-	V
	RS2DAF-T	$I_F = 2A, T_J = 25^{\circ}C$		0.93	1.30	V
	RS2GAF-T	$I_F = 1A, T_J = 125^{\circ}C$		0.71	-	V
–		$I_F = 2A, T_J = 125^{\circ}C$		0.80	0.94	V
Forward voltage ⁽¹⁾		$I_F = 1A, T_J = 25^{\circ}C$	- V _F	1.04	-	V
	RS2JAF-T	$I_F = 2A, T_J = 25^{\circ}C$		1.14	1.30	V
	RS2KAF-T RS2MAF-T	$I_F = 1A, T_J = 125^{\circ}C$		0.87	-	V
		$I_F = 2A, T_J = 125^{\circ}C$		0.98	1.23	V
		$T_J = 25^{\circ}C$		-	5	μA
Reverse current @ rated $V_R^{(2)}$		T _J = 125°C	– I _R	-	100	μA
RS2DAF-T RS2GAF-T			0.54 1 1.04	-	150	ns
Reverse recovery time	RS2JAF-T RS2KAF-T RS2MAF-T	I _F = 0.5A, I _R = 1.0A I _{rr} = 0.25A	t _{rr}	-	250	ns
	RS2DAF-T RS2GAF-T		CJ	21	-	pF
Junction capacitance	RS2JAF-T RS2KAF-T RS2MAF-T	1MHz, V _R = 4.0V		10	-	pF

Notes:

1. Pulse test with PW = 0.3ms

2. Pulse test with PW = 30ms

ORDERING INFORMATION			
ORDERING CODE ⁽¹⁾	PACKAGE	PACKING	
RS2xAF-T	SMAF	7,500 / Tape & Reel	

Notes:

1. "x" defines voltage from 200V (RS2DAF-T) to 1000V (RS2MAF-T)



Taiwan Semiconductor

CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

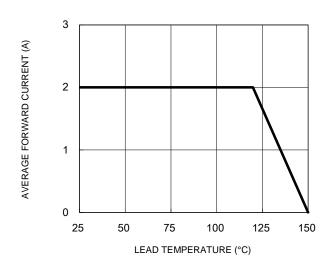


Fig.1 Forward Current Derating Curve

Fig.3 Typical Reverse Characteristics

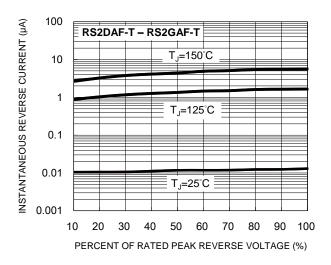
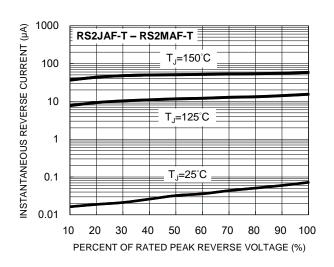


Fig.5 Typical Reverse Characteristics



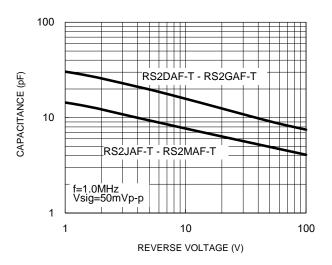


Fig.2 Typical Junction Capacitance



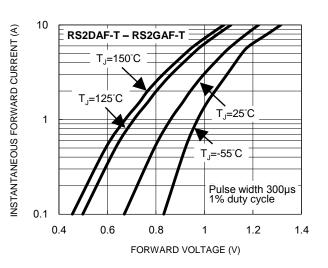
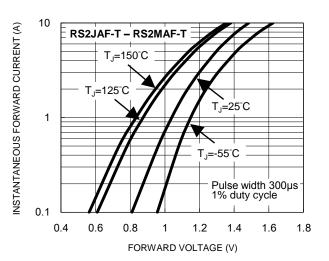


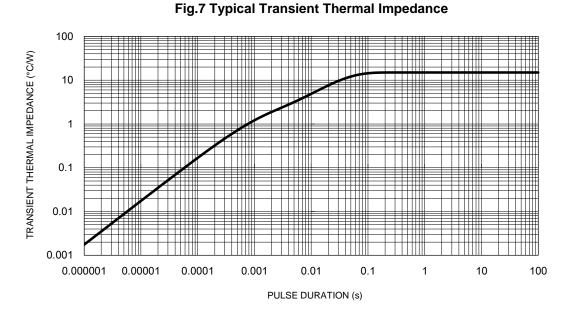
Fig.6 Typical Forward Characteristics





CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

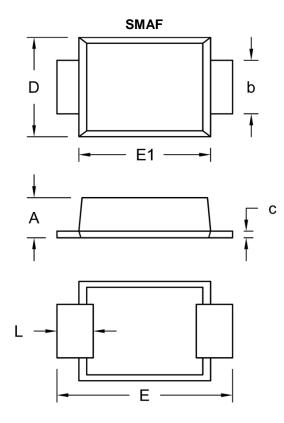




RS2DAF-T – RS2MAF-T

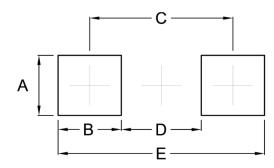
Taiwan Semiconductor

PACKAGE OUTLINE DIMENSIONS



DIM. Unit		(mm)	Unit (inch)	
	Min.	Max.	Min.	Max.
A	1.00	1.10	0.039	0.043
b	1.30	1.50	0.051	0.059
С	0.10	0.25	0.004	0.010
D	2.40	2.80	0.094	0.110
E	4.40	4.80	0.173	0.189
E1	3.25	3.65	0.128	0.144
L	0.70	1.20	0.028	0.047

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	1.57	0.062
В	1.66	0.065
С	3.76	0.148
D	2.10	0.083
E	5.42	0.213

MARKING DIAGRAM



P/N = Marking Code

G = Green Compound

YW = Date Code

F = Factory Code



RS2DAF-T – RS2MAF-T

Taiwan Semiconductor

Notice

Specifications of the products displayed herein are subject to change without notice. TSC or anyone on its behalf, assumes no responsibility or liability for any errors or inaccuracies.

Purchasers are solely responsible for the choice, selection, and use of TSC products and TSC assumes no liability for application assistance or the design of Purchasers' products.

Information contained herein is intended to provide a product description only. No license, express or implied, to any intellectual property rights is granted by this document. Except as provided in TSC's terms and conditions of sale for such products, TSC assumes no liability whatsoever, and disclaims any express or implied warranty, relating to sale and/or use of TSC products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright, or other intellectual property right.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications. Customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify TSC for any damages resulting from such improper use or sale.